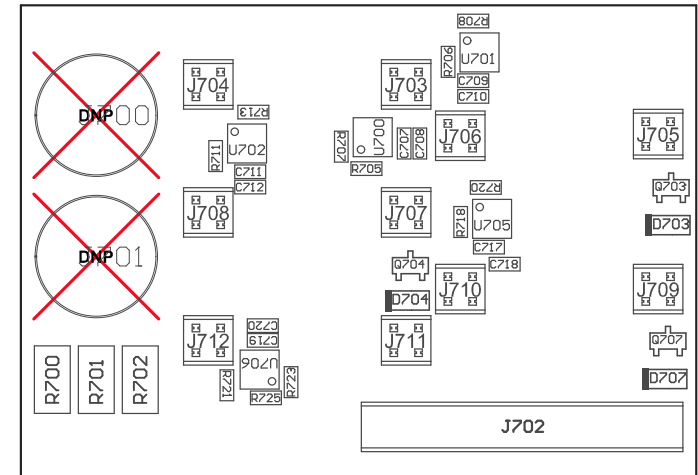


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20637_Load Rev D	SUN REV: Not In VersionControl
	TID #: N/A	
PLOT NAME = Top Assembly Drawing	GENERATED : 2/17/2017 1:20:08 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20637_Load Board D	SUN REV: Not In VersionControl
	TID #: N/A	
PLOT NAME = Bottom Assembly Drawing	GENERATED : 2/17/2017 1:20:09 PM	TEXAS INSTRUMENTS

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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